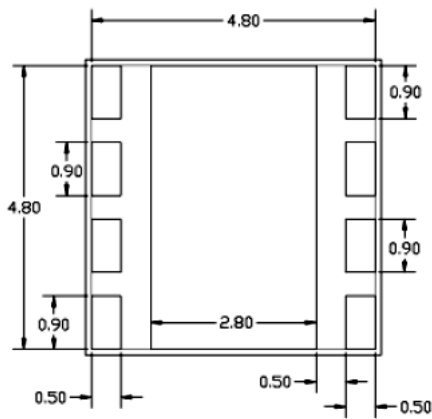
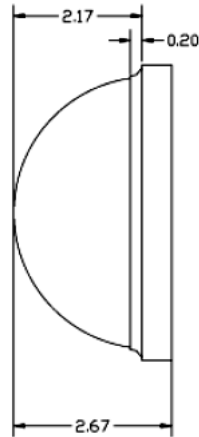
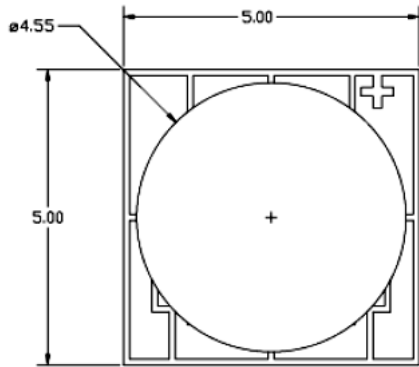


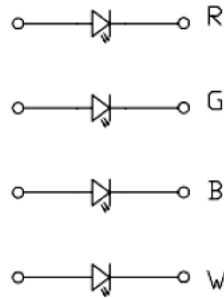
SPECIFICATION FOR APPROVAL

Part No. : YLE-5050RGBNW-1W-MU

Package Dimensions

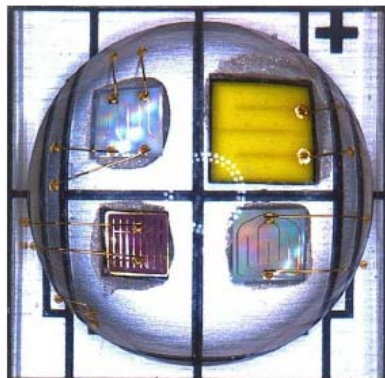


Circuit Diagram



Anode(+)

Cathode(-)



Part NO.	Chip Material				Lens Color	Emission Color
	White	Red	Green	Blue		
YLE-5050RGBNW-1WMU	InGaN	AlGaInP	InGaN	InGaN	Water Clear	White & Red &Green& Blue

Notes:

1. All dimensions are in millimeters.
2. Tolerance is $\pm 0.25\text{mm} (.010\text{'})$ unless otherwise noted.

➤ Electrical/Optical Characteristics (I_F= 350mA Ta=25°C)

Color	Dominate Wavelength (nm)		Luminous Flux (lm)		Forward Voltage (V)		View angle
	Color Temperature		Radiant Flux (mW)		Min.	Max.	
	Min.	Max.	Min.	Max.			
Red	620 nm	630 nm	28 lm	48 lm	2.0	2.8	140°
Green	520 nm	535 nm	57 lm	90 lm	3.0	3.8	
Blue	450 nm	460 nm	280 mW	360 mW	3.0	3.8	
White	5300K	8000K	100 lm	120 lm	3.0	3.6	

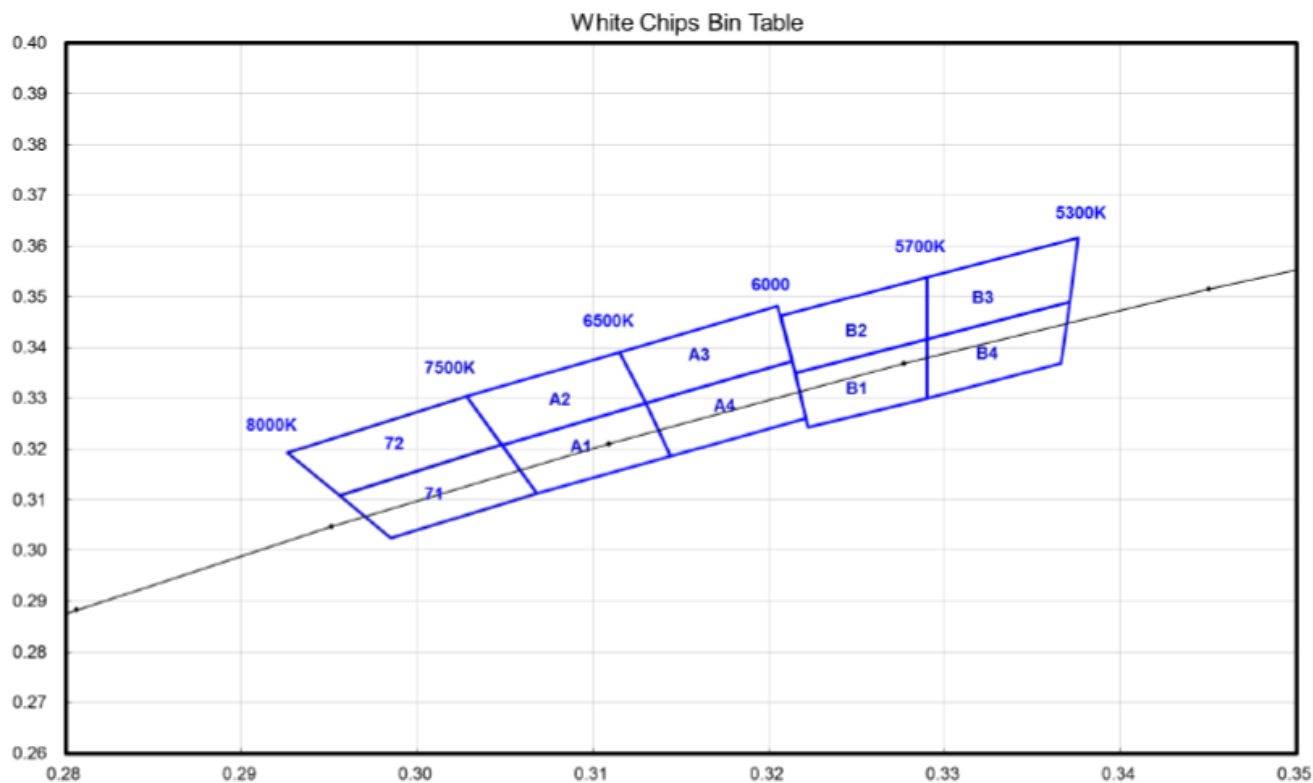
➤ Absolute Maximum Rating (Ta=25°C)

Parameter	Symbol	Ratings	Units
Continuous Forward Current-Red	I _F	350	mA
Continuous Forward Current-Green	I _F	350	mA
Continuous Forward Current-Blue	I _F	350	mA
Continuous Forward Current-White	I _F	350	mA
Operating Temperature Range	T _{OPR}	-30°C To +80°C	
Storage Temperature Range	T _{STG}	-40°C To +100°C	
Manual Solding Temperature	T _{SOL}	260°C±20°C For 3-5 Seconds	

Notes

[1]. Tolerance Θ:10°

➤ BIN Structure



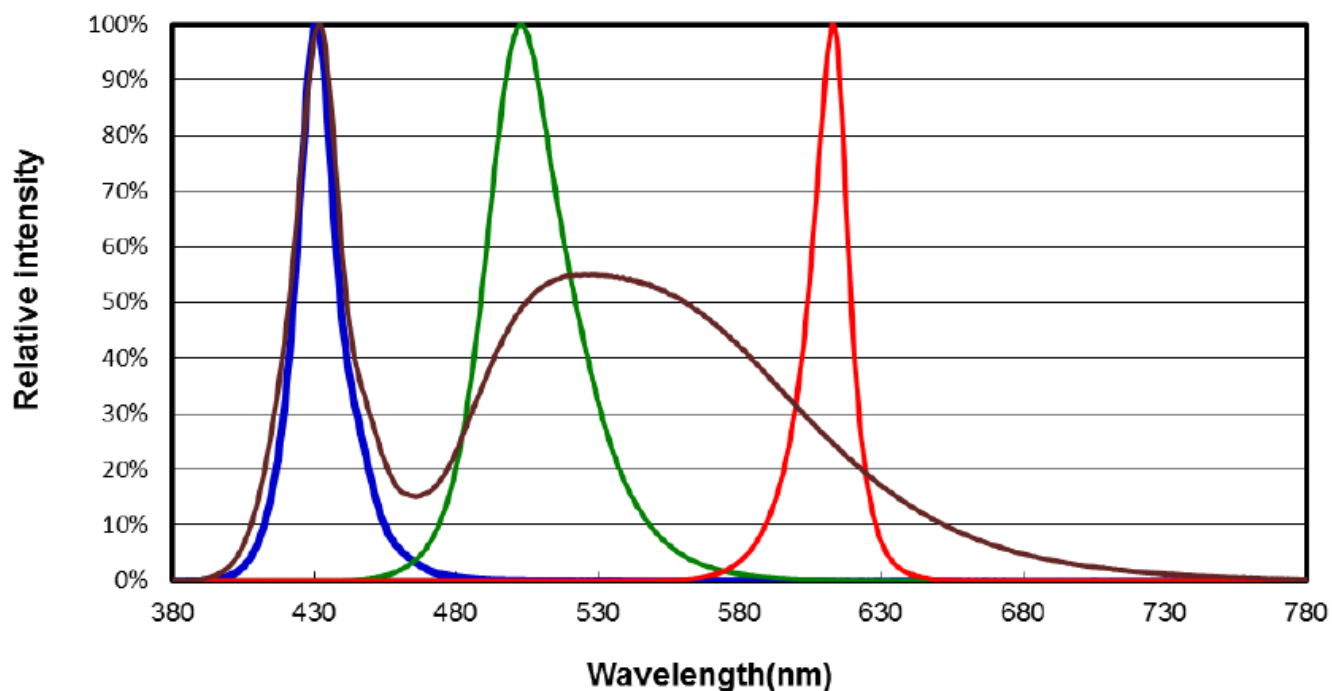
➤ Bin Coordinates

CCT	Bin code	x	y
5650~6000	B1	0.3215	0.3350
		0.3290	0.3417
		0.3290	0.3300
		0.3222	0.3243
	B2	0.3207	0.3462
		0.3290	0.3538
5300~5650	B3	0.3290	0.3538
		0.3376	0.3616
		0.3371	0.3490
		0.3290	0.3417
	B4	0.3290	0.3417
		0.3371	0.3490
		0.3366	0.3369
		0.3290	0.3300

CCT	Bin code	x	y
6500~7000	A1	0.3048	0.3207
		0.3130	0.3290
		0.3144	0.3186
		0.3068	0.3113
	A2	0.3028	0.3304
		0.3115	0.3391
6000~6500	A3	0.3115	0.3391
		0.3205	0.3481
		0.3213	0.3373
		0.3130	0.3290
	A4	0.3130	0.3290
		0.3213	0.3373
		0.3221	0.3261
		0.3144	0.3186

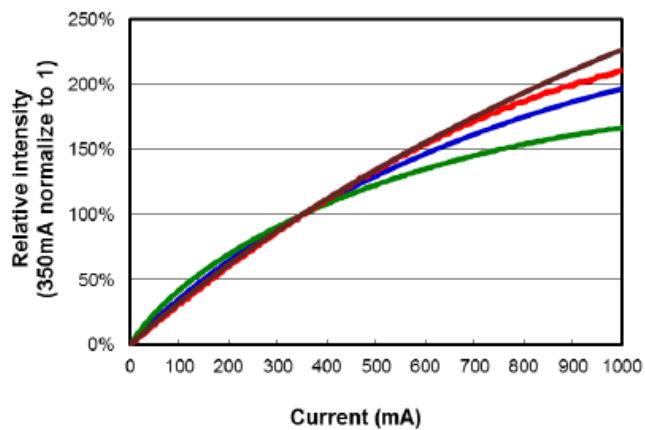
CCT	Bin code	x	y
7000~8000	71	0.2926	0.3193
		0.2956	0.3109
		0.3048	0.3209
		0.3028	0.3304
	72	0.2956	0.3109
		0.2985	0.3025
		0.3068	0.3113
		0.3048	0.3209

☰ Spectrum Distribution

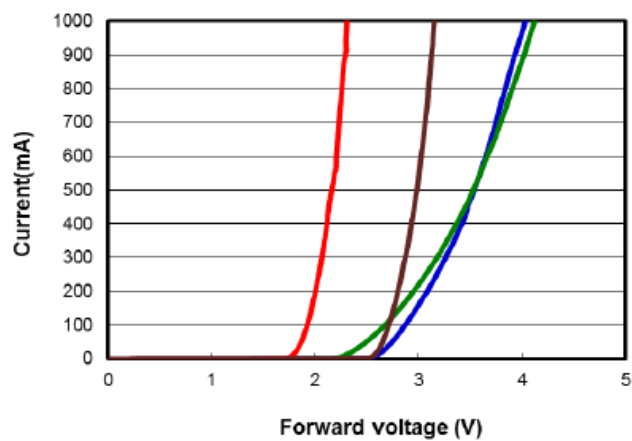


☰ Characteristic Curves

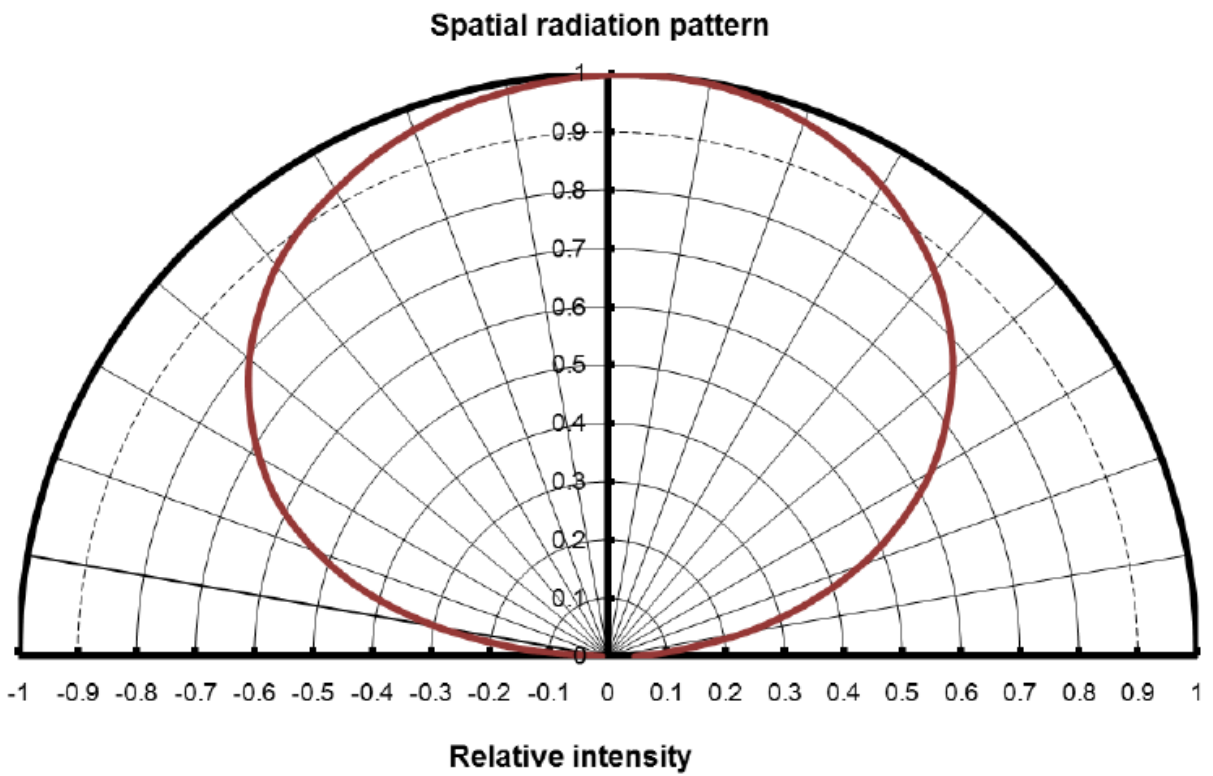
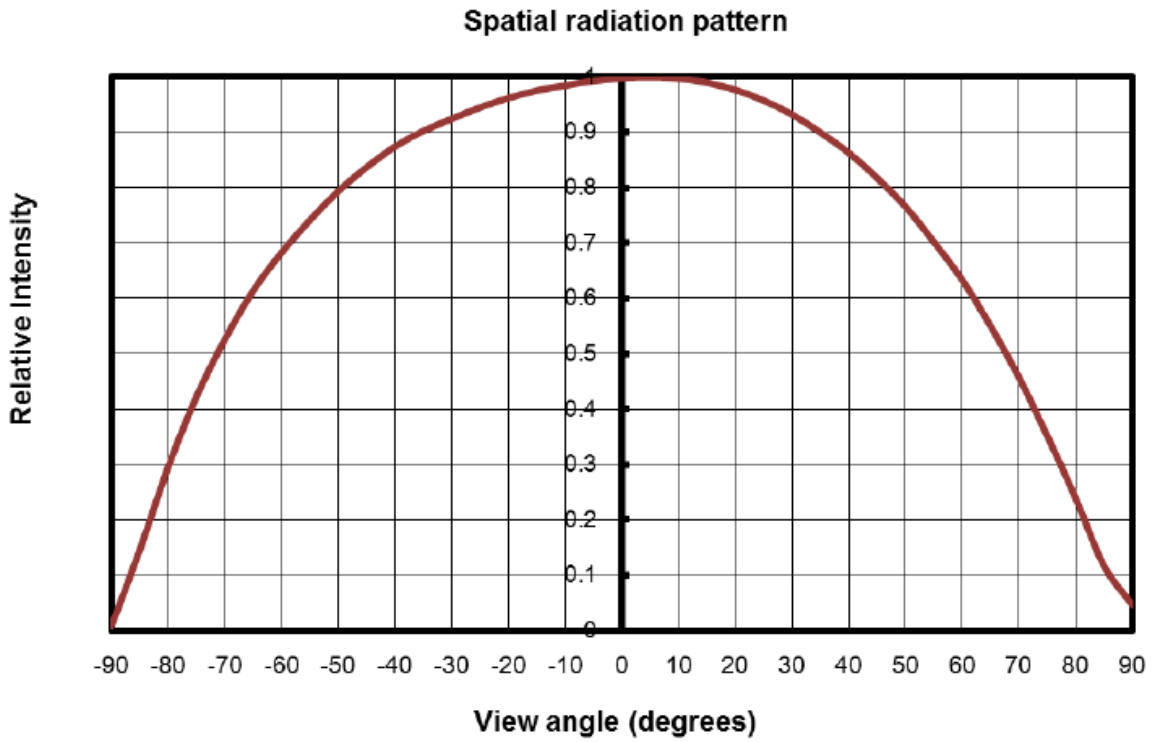
Luminous flux (Φ_v) vs Current (I_F)



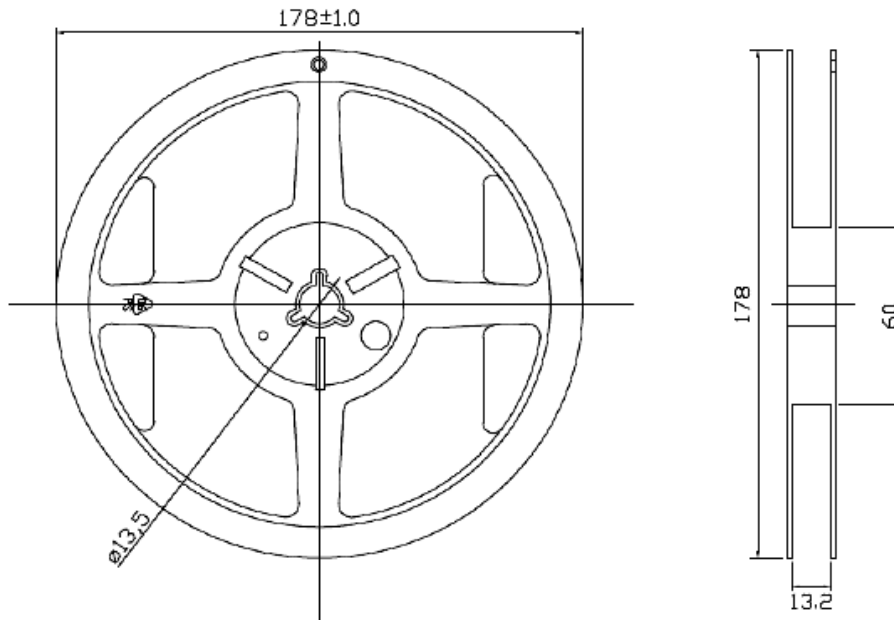
Current (I_F) vs Voltage (V_F)



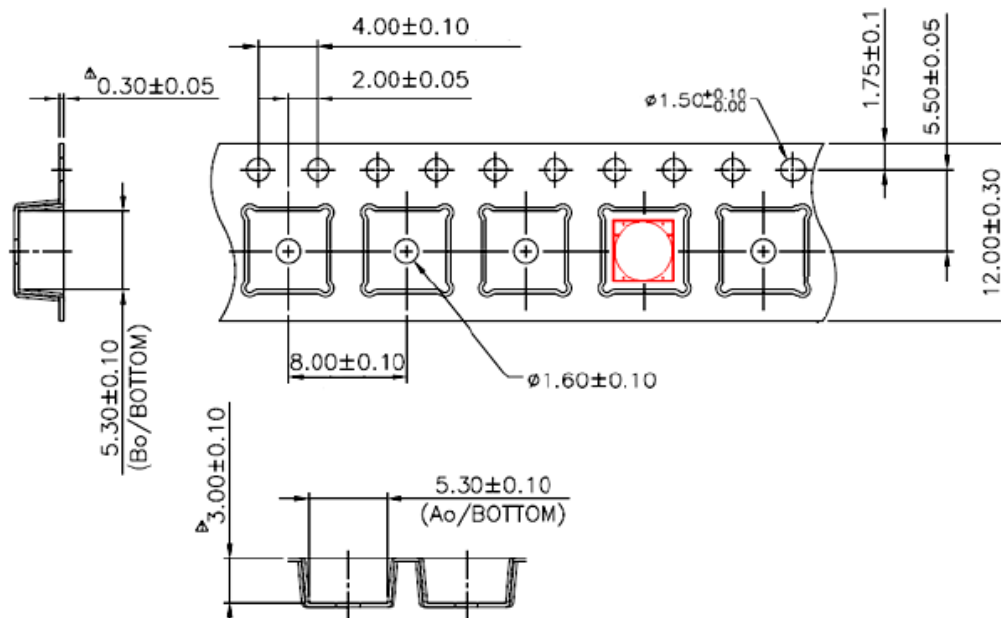
➤ Typical Radiation Pattern



- **Packing**
Tape-and-Reel packing
- **Reel dimensions**



- **Carrier tape dimensions**



Unit : mm

☞ Notice

1. In order to avoid absorption of moisture, it is recommended that the products are stored in the dry box (or desiccators) with a desiccants. Alternatively the following environment is recommended:
Storage temperature: 5°C~30°C Humidity: 60% HR max.
2. If the storage conditions are of high humidity the product should be dried before use. Recommended drying conditions: 12 hours at 100°C±5°C
3. Any mechanical force or any excess vibration should be avoided during the cooling process after soldering.
4. Reflow rapidly cooling should be avoided.
5. Components should not be mounted on distorted Printed Circuit Boards.
6. Devices should not contact with any types of fluid, such as water, oil, organic solvents.... etc.
7. The maximum ambient temperature should be taken into consideration when determining the operating current.
8. Devices should be soldered within 7 days after opening the moisture-proof packing.
9. Repack unused product in anti-moisture packing, fold to close any opening and store in a dry place.
10. The appearance and specifications of devices may be modified for improvement without notice.
11. ESD Precautions Static Electricity and surge damages LEDs. It is recommended that wrist bands or anti-electrostatic gloves be used when handling the LEDs. All devices, equipment and machinery should be properly grounded.
12. This product must be driven by constant power supplier.